

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MIRCEA GUNA	02/01/2023
RECEIVING PARTY DATA	
Name:	DH TECHNOLOGIES DEVELOPMENT PTE. LTD.
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City:	SINGAPORE
State/Country:	SINGAPORE
Postal Code:	739256
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17274105
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	ABS-0438US
NAME OF SUBMITTER:	PATRICIA TOCCI
SIGNATURE:	/Patricia Tocci/
DATE SIGNED:	02/21/2023
Total Attachments: 2	
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WORLDWIDE ASSIGNMENT

For good and valuable consideration paid to me/us, receipt of which is hereby acknowledged,
I/we:

Mircea Guna, having an address at Sciex, 71 Four Valley Drive, Concord, Ontario L4K 4V8
Canada;

do hereby sell, assign, and set over unto:

DH Technologies Development Pte. Ltd.
33 Marsiling Industrial Estate Road 3, #04-06, Singapore, 739256

(hereinafter "Assignee"), their successors, legal representatives and assigns my/our entire right, title,
and interest in and to any and all of my/our inventions and discoveries entitled:

RF Ion Trap Ion Loading Method

as described and/or claimed in my/our:

	SERIAL NUMBER	DATE FILED
U.S. Patent Application No.	17/274,105	March 5, 2021
Corresponding to PCT Application No.	PCT/IB2019/057463	September 4, 2019
Claiming Priority to US Provisional Appl. No.	62/728,642	September 7, 2018

in and to the right to file patent applications in the name of Assignee, its designee, in my/our name(s),
or in any other name or names, on the aforesaid inventions and discoveries in any or all countries of
the world, together with all rights of priority in the aforesaid countries deriving from the above-
identified United States patent application, in and to any and all applications for Letters Patent, and
any and all Letters Patent that issue on any of the aforesaid applications, and in and to any and all
divisions, continuations, and continuations-in-part of any and all of said applications, and any and all
reissues, renewals and extensions of any of said Letters Patent, such that the same right, title and
interest to be held and enjoyed by Assignee, its successors, assigns or other legal representatives, to
the full ends of the terms for which all Letters Patent therefor may be granted, shall be as full and
complete as that that would have been held and enjoyed by me/us if this assignment and sale had not
been made.

I/We further hereby covenant and agree, for the same consideration, whenever counsel of
Assignee, or the counsel of its successors, legal representatives and assigns, shall advise that any
proceeding in connection with said inventions, or said application for Letters Patent, or any proceeding
in connection with said invention, or said application for Letters Patent, including interference
proceedings, is lawful and desirable, or that any division, continuation, or continuation-in-part of any
application for Letters Patent, or any reissue or extension of any Letters Patent, to be obtained thereon,
is lawful and desirable to sign all papers and documents, take all lawful oaths, and do all acts necessary
or required to be done for the procurement, maintenance, enforcement and defense of Letters Patent
for said invention, without charge to said Assignee, its successors, legal representatives and assigns,
but at the cost and expense of said Assignee, its successors, legal representatives and assigns.

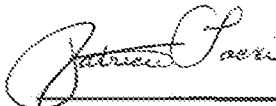
If not already entered at the time of signing, I/we hereby authorize Assignee to insert in this instrument the serial number(s) and filing date(s) of said application(s) when officially notified thereof.

SIGNED this 1 day of February, 2023, at Concord, ON, Canada
(City/Town, State/Province and Country)


Assignor: **Mircea Guna**

ASSIGNEE, DH Technologies Development Pte. Ltd., hereby acknowledges receipt of the entire right, title and interest in and to the aforementioned patent applications and patents.

SIGNED this 21st _____ day of February, 2023, at Framingham, Massachusetts
US.


Attorney-in-Fact
Patricia Tocci